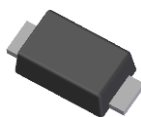


Features

- 1W Power Dissipation on FR-4 PCB
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**
<https://www.diodes.com/quality/product-definitions/>
- **An automotive-compliant part is available under separate datasheet (DFLZ5V1Q - DFLZ39Q)**

Mechanical Data

- Package: PowerDI[®]123
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.01 grams (Approximate)



Top View

Ordering Information (Note 4)

Part Number	Package	Packing	
		Quantity	Carrier
(Type Number)-7*	PowerDI123	3,000	Tape & Reel
(Type Number)-13**	PowerDI123	10,000	Tape & Reel

* Add "-7" to the appropriate type number in Electrical Characteristics Table. Example: 16V Zener = DFLZ16-7

** Add "-13" to the appropriate type number in Electrical Characteristics Table. Example: 16V Zener = DFLZ16-13

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



Fxx = Product Type Marking Code
 (See Electrical Characteristics Table)
 YM = Date Code Marking
 Y = Year (ex: K = 2023)
 M = Month (ex: 9 = September)

Date Code Key

Year	2014	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	B	K	L	M	N	O	P	R	S	T	U
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 200mA	V _F	1.2	V

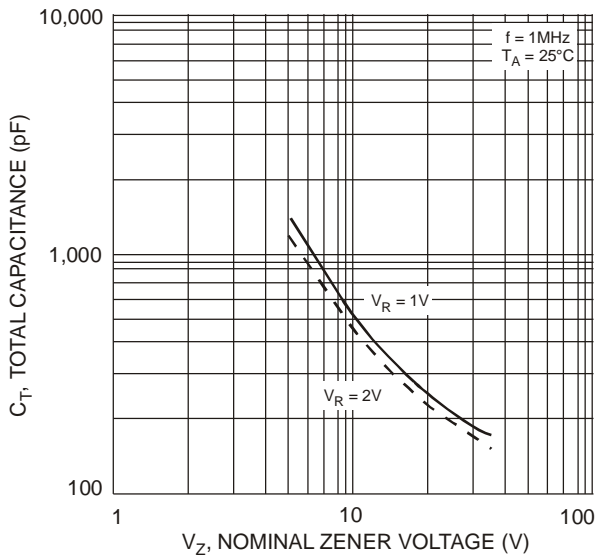
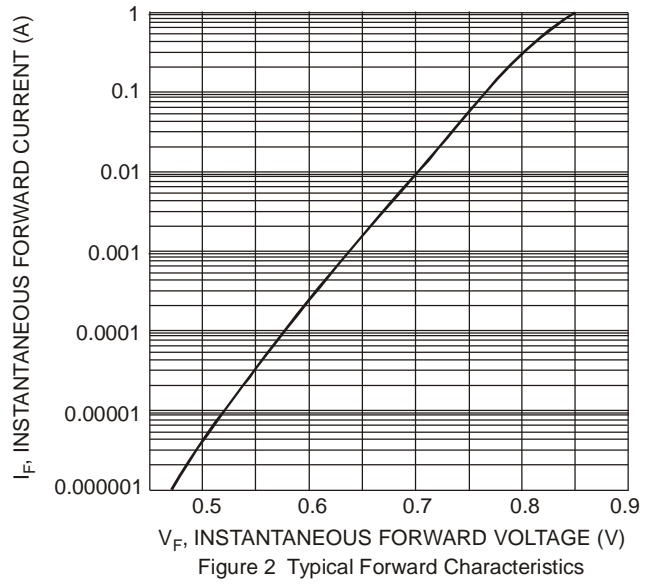
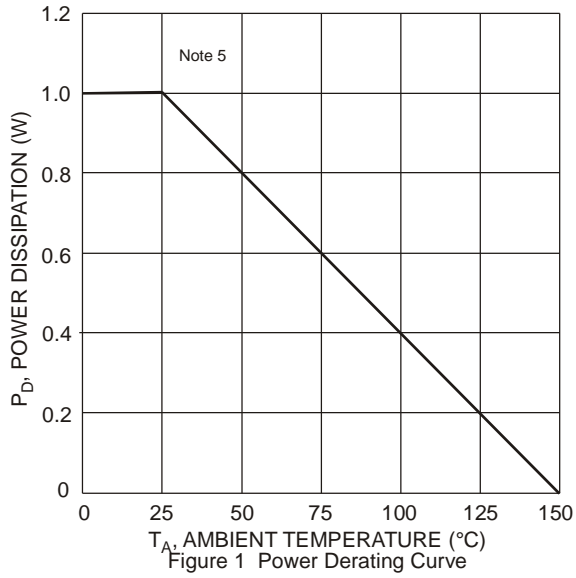
Thermal Characteristics

Characteristic	Symbol	Typ	Value	Unit
Power Dissipation (Note 5)	P _D	—	1.0	W
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	110	—	°C/W
Thermal Resistance Junction to Soldering Point (Note 6)	R _{θJS}	—	9	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	—	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Type Number	Marking Codes	Zener Voltage Range (Note 7)				Zener Impedance		Maximum Reverse Current (Note 7)		Temperature Coefficient @ I _{ZTC} %/°C	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}		I _R	@ V _R	Min	Max
		Nom (V)	Min (V)	Max (V)	mA	Typ (Ω)	Max (Ω)	μA	V		
DFLZ5V1	FHK	5.1	4.8	5.4	100	2	6	2.5	1	-0.08	0.02
DFLZ5V6	FHL	5.6	5.2	6.0	100	1	4	10	2	-0.04	0.04
DFLZ6V2	FHN	6.2	5.8	6.6	100	1	3	5	2	-0.01	0.06
DFLZ6V8	FHO	6.8	6.4	7.2	100	1	3	5	3	0	0.07
DFLZ7V5	FHQ	7.5	7.0	7.9	100	1	2	5	3	0	0.07
DFLZ8V2	FHR	8.2	7.7	8.7	100	1	2	5	3	0.03	0.08
DFLZ9V1	FHT	9.1	8.5	9.6	50	1	4	5	5	0.03	0.08
DFLZ10	FHU	10	9.4	10.6	50	1	4	5	7.5	0.05	0.09
DFLZ11	FHV	11	10.4	11.6	50	1	7	4	8.2	0.05	0.10
DFLZ12	FHW	12	11.4	12.7	50	1	7	3	9.1	0.05	0.10
DFLZ13	FHX	13	12.4	14.1	50	1	10	2	10	0.05	0.10
DFLZ15	FHZ	15	13.8	15.6	50	1	10	1	11	0.05	0.10
DFLZ16	FJA	16	15.3	17.1	25	1	15	1	12	0.06	0.11
DFLZ18	FJF	18	16.8	19.1	25	2	15	1	13	0.06	0.11
DFLZ20	FJG	20	18.8	21.2	25	3	15	1	15	0.06	0.11
DFLZ22	FJK	22	20.8	23.3	25	3	15	1	16	0.06	0.11
DFLZ24	FJL	24	22.8	25.6	25	2	15	1	18	0.06	0.11
DFLZ27	FJN	27	25.1	28.9	25	3	15	1	20	0.06	0.11
DFLZ30	FJQ	30	28	32	25	8	15	1	22	0.06	0.11
DFLZ33	FJR	33	31	35	25	5	15	1	24	0.06	0.11
DFLZ36	FJS	36	34	38	10	5	40	1	27	0.06	0.11
DFLZ39	FJT	39	37	41	10	5	40	1	30	0.06	0.11

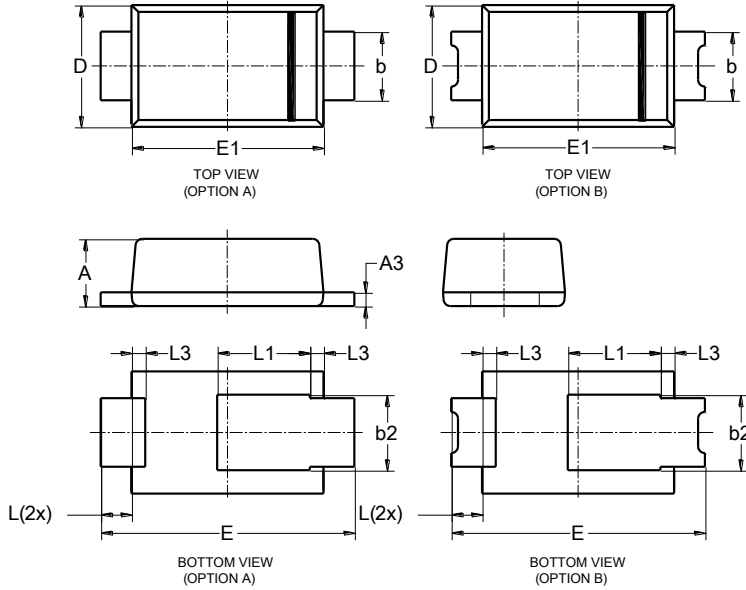
- Notes:
- Device mounted on 1.5" x 1.5", FR-4 PCB; 2 oz. Cu with 1"x1" pad layout.
 - Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 - Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123

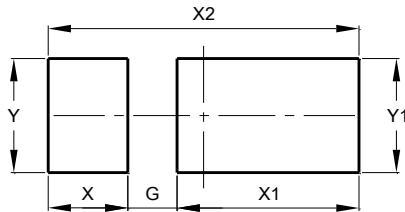


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

IMPORTANT NOTICE

1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
5. Diodes' products are provided subject to Diodes' Standard Terms and Conditions of Sale (<https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/>) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
9. This Notice may be periodically updated with the most recent version available at <https://www.diodes.com/about/company/terms-and-conditions/important-notice>

The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries.
All other trademarks are the property of their respective owners.
© 2023 Diodes Incorporated. All Rights Reserved.

www.diodes.com